

# FDMS8660S

## N-Channel PowerTrench® SyncFET™

30V, 40A, 2.4mΩ

### Features

- Max  $r_{DS(on)}$  = 2.4mΩ at  $V_{GS} = 10V$ ,  $I_D = 25A$
- Max  $r_{DS(on)}$  = 3.5mΩ at  $V_{GS} = 4.5V$ ,  $I_D = 21A$
- Advanced Package and Silicon combination for low  $r_{DS(on)}$  and high efficiency
- SyncFET Schottky Body Diode
- MSL1 robust package design
- RoHS Compliant



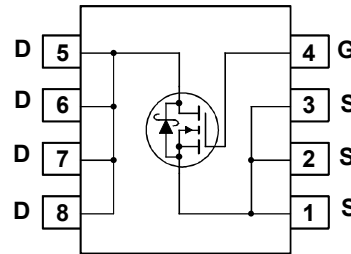
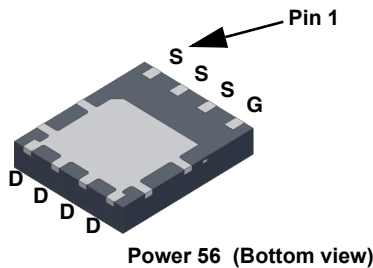
### General Description

The FDMS8660S has been designed to minimize losses in power conversion applications. Advancements in both silicon and package technologies have been combined to offer the lowest  $r_{DS(on)}$  while maintaining excellent switching performance. This device has the added benefit of an efficient monolithic Schottky body diode.

### Application

Synchronous Rectifier for DC/DC Converters

- Notebook Vcore/ GPU low side switch
- Networking Point of Load low side switch
- Telecom secondary side rectification



### MOSFET Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain to Source Voltage	30	V
$V_{GS}$	Gate to Source Voltage	±20	V
$I_D$	Drain Current -Continuous (Package limited) $T_C = 25^\circ\text{C}$	40	A
	-Continuous (Silicon limited) $T_C = 25^\circ\text{C}$	147	
	-Continuous $T_A = 25^\circ\text{C}$ (Note 1a)	25	
	-Pulsed	200	
$P_D$	Power Dissipation $T_C = 25^\circ\text{C}$	83	W
	Power Dissipation $T_A = 25^\circ\text{C}$ (Note 1a)	2.5	
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

### Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.5	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	

### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS8660S	FDMS8660S	Power 56	13"	12mm	3000 units

## Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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### Off Characteristics

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 1\text{mA}, V_{GS} = 0\text{V}$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 1\text{mA}$ , referenced to $25^\circ\text{C}$		35		$\text{mV}/^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 24\text{V}, V_{GS} = 0\text{V}$			500	$\mu\text{A}$
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$			$\pm 100$	nA

### On Characteristics (Note 2)

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 1\text{mA}$	1	1.5	2	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 1\text{mA}$ , referenced to $25^\circ\text{C}$		-6		$\text{mV}/^\circ\text{C}$
$r_{DS(on)}$	Drain to Source On Resistance	$V_{GS} = 10\text{V}, I_D = 25\text{A}$		1.9	2.4	m $\Omega$
		$V_{GS} = 4.5\text{V}, I_D = 21\text{A}$		2.6	3.5	
		$V_{GS} = 10\text{V}, I_D = 25\text{A}, T_J = 125^\circ\text{C}$		2.9	3.9	
$g_{FS}$	Forward Transconductance	$V_{DS} = 10\text{V}, I_D = 25\text{A}$		123		S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 15\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		4345		pF
$C_{oss}$	Output Capacitance			1215		pF
$C_{rss}$	Reverse Transfer Capacitance			425		pF
$R_g$	Gate Resistance	$f = 1\text{MHz}$		1.0		$\Omega$

### Switching Characteristics

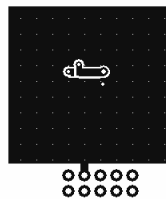
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 15\text{V}, I_D = 1\text{A}$ $V_{GS} = 10\text{V}, R_{GEN} = 6\Omega$		17	31	ns	
$t_r$	Rise Time			12	22	ns	
$t_{d(off)}$	Turn-Off Delay Time			76	122	ns	
$t_f$	Fall Time			50	80	ns	
$Q_{g(TOT)}$	Total Gate Charge at 10V		$V_{GS} = 0\text{V}$ to 10V		81	113	nC
$Q_{g(4.5V)}$	Total Gate Charge at 4.5V	$V_{GS} = 0\text{V}$ to 4.5V	$V_{DS} = 15\text{V}$ $I_D = 25\text{A}$		44	62	nC
$Q_{gs}$	Gate to Source Gate Charge				11		nC
$Q_{gd}$	Gate to Drain "Miller" Charge				16		nC

### Drain-Source Diode Characteristics

$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 2.2\text{A}$ (Note 2)		0.37	0.70	V
$t_{rr}$	Reverse Recovery Time	$I_F = 25\text{A}, di/dt = 300\text{A}/\mu\text{s}$		35		ns
$Q_{rr}$	Reverse Recovery Charge			98		nC

#### Notes:

1:  $R_{\theta JA}$  is determined with the device mounted on a  $1\text{in}^2$  pad 2 oz copper pad on a  $1.5 \times 1.5\text{in.}$  board of FR-4 material.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.



a.  $50^\circ\text{C}/\text{W}$  when mounted on a  $1\text{in}^2$  pad of 2 oz copper



b.  $125^\circ\text{C}/\text{W}$  when mounted on a minimum pad of 2 oz copper

Scale 1 : 1 on letter size paper

2: Pulse Test: Pulse Width <  $300\mu\text{s}$ , Duty cycle < 2.0%.

**Typical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted

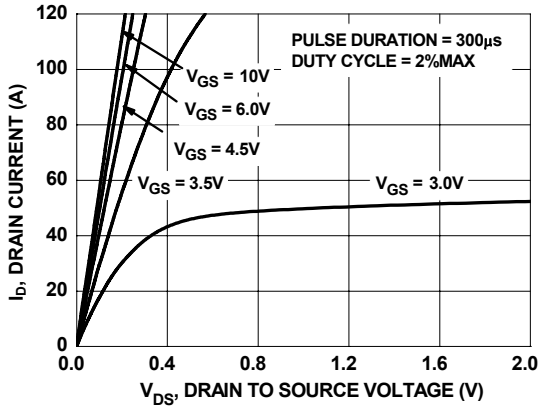


Figure 1. On-Region Characteristics

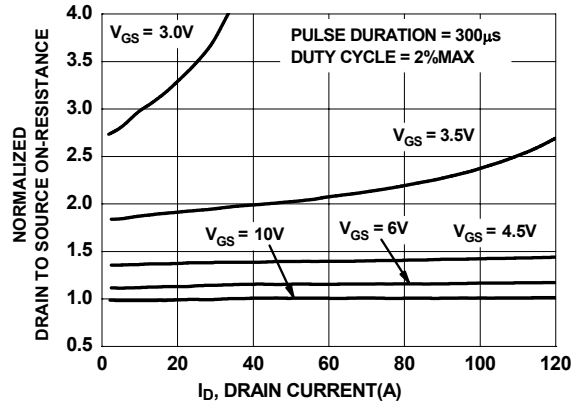


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

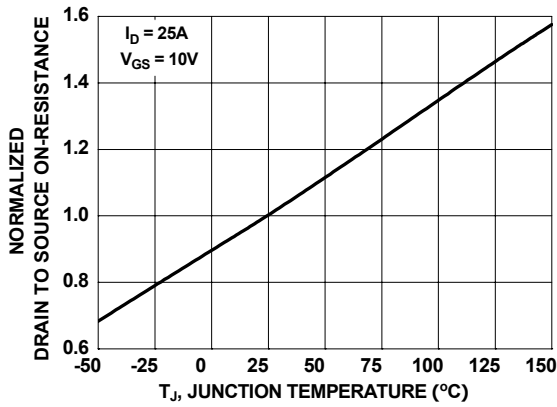


Figure 3. Normalized On-Resistance vs Junction Temperature

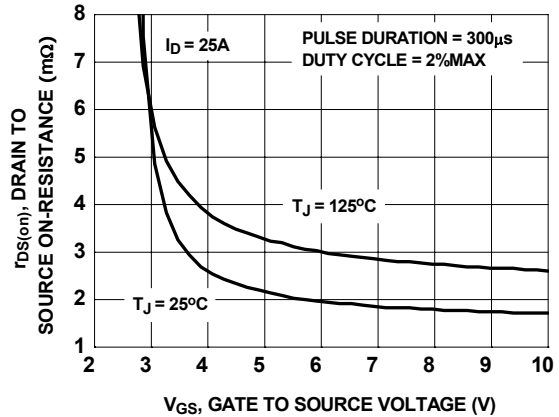


Figure 4. On-Resistance vs Gate to Source Voltage

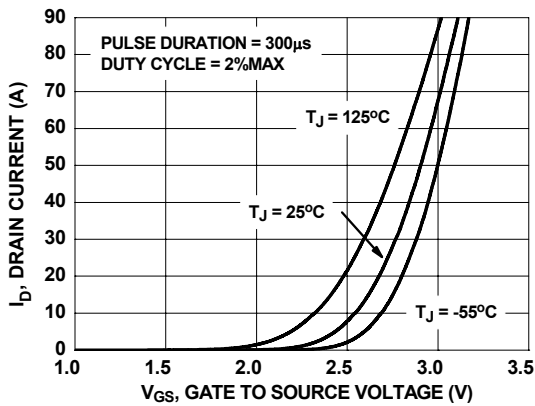


Figure 5. Transfer Characteristics

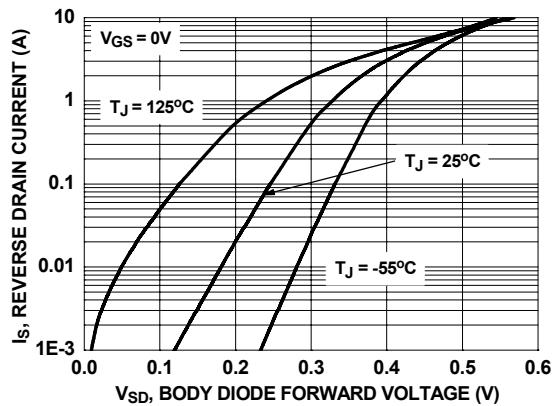
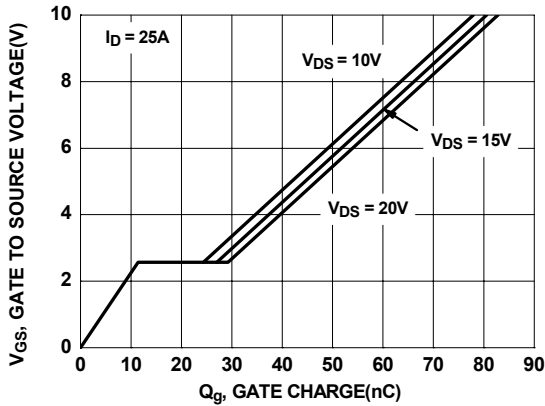
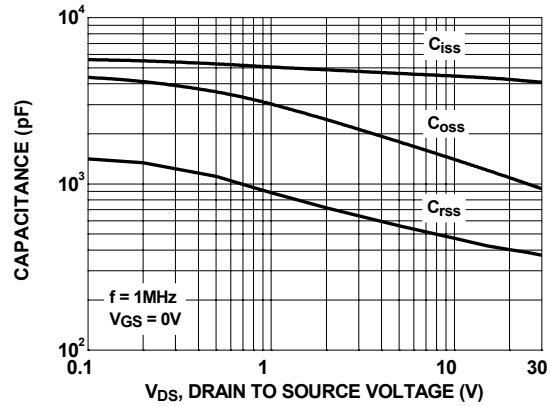


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

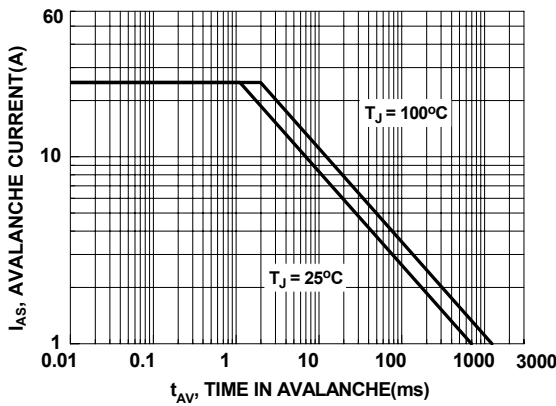
**Typical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted



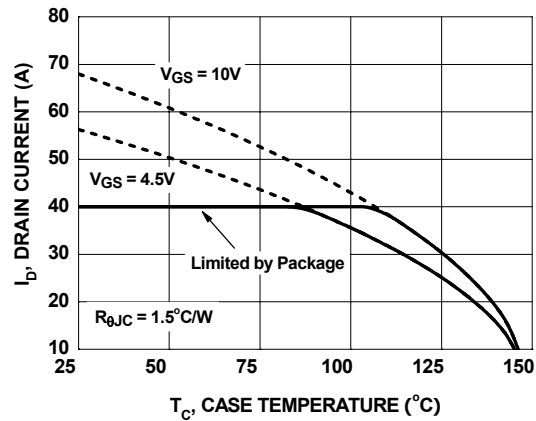
**Figure 7. Gate Charge Characteristics**



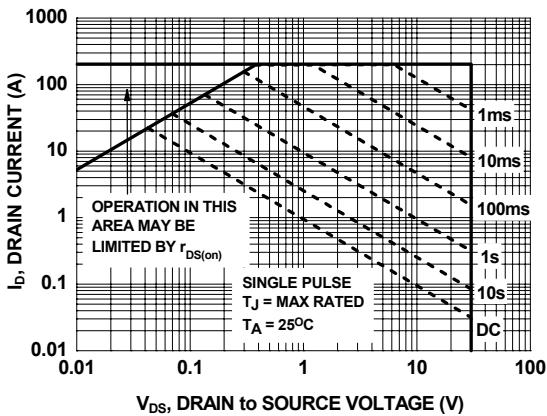
**Figure 8. Capacitance vs Drain to Source Voltage**



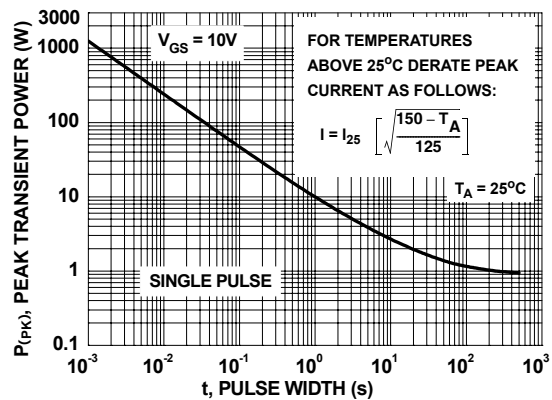
**Figure 9. Unclamped Inductive Switching Capability**



**Figure 10. Maximum Continuous Drain Current vs Case Temperature**

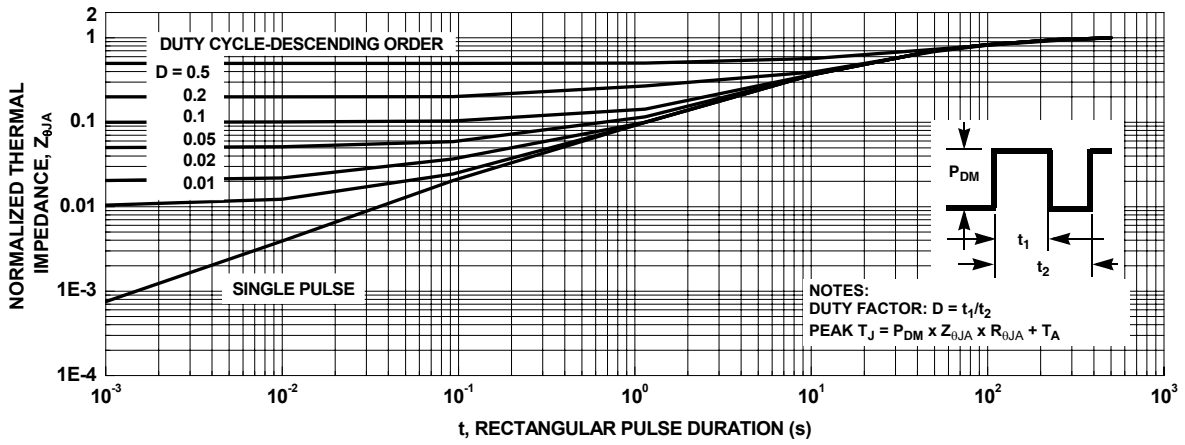


**Figure 11. Forward Bias Safe Operating Area**



**Figure 12. Single Pulse Maximum Power Dissipation**

**Typical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted



## Typical Characteristics (continued)

### SyncFET Schottky body diode Characteristics

Fairchild's SyncFET process embeds a Schottky diode in parallel with PowerTrench MoSFET. This diode exhibits similar characteristics to a discrete external Schottky diode in parallel with a MOSFET. Figure 14 shows the reverse recovery characteristic of the FDMS8660S.

Schottky barrier diodes exhibit significant leakage at high temperature and high reverse voltage. This will increase the power in the device.

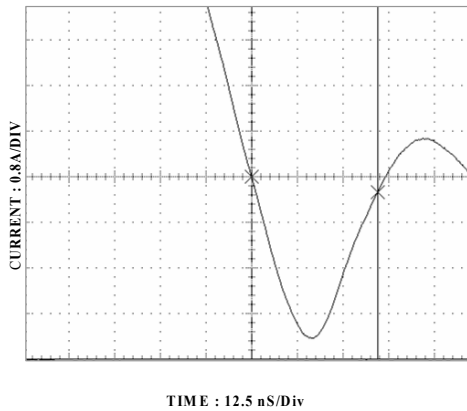


Figure 14. FDMS8660S SyncFET body diode reverse recovery characteristic

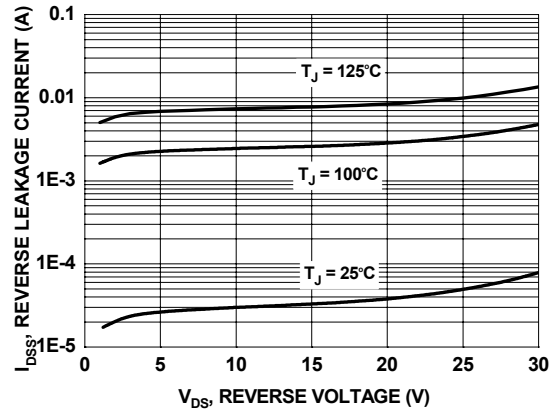


Figure 15. SyncFET body diode reverse leakage versus drain-source voltage



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Rev. 121